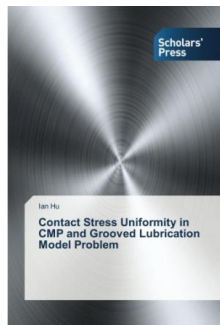


Find PDF

CONTACT STRESS UNIFORMITY IN CMP AND GROOVED LUBRICATION MODEL PROBLEM



Condition: New. Publisher/Verlag: Scholar's Press | This work includes two parts. First, we use 2D models of fluid film lubrication and contact mechanics to calculate the contact stress and fluid (i.e., slurry) pressure distributions on the wafer pad interface in chemical mechanical planarization (CMP). Our numerical results indicate that, the resulting minimum contact stress non-uniformity (NU), which directly affects the spatial uniformity of the material removal rate on the wafer surface, decreases with the effective wafer rigidity (determined by the...

Download PDF Contact Stress Uniformity in CMP and Grooved Lubrication Model Problem

- Authored by Hu, Ian
- Released at -



File size: 4.63 MB

Reviews

This publication is wonderful. it was actually writtem very completely and beneficial. You may like the way the writer compose this publication.

-- **Prof. Aisha Mosciski PhD**

This ebook is great. I really could comprehended every thing using this composed e ebook. Its been designed in an exceedingly simple way and it is only follo wing i finished reading this publication where basically modified me, modify the way in my opinion.

-- **Herminia Blanda**

It in a single of my favorite pdf. Yes, it is engage in, still an amazing and interesting literature. It is extremely difficult to leave it before concluding, once you begin to read the book.

-- **Dr. Keeley Windler**